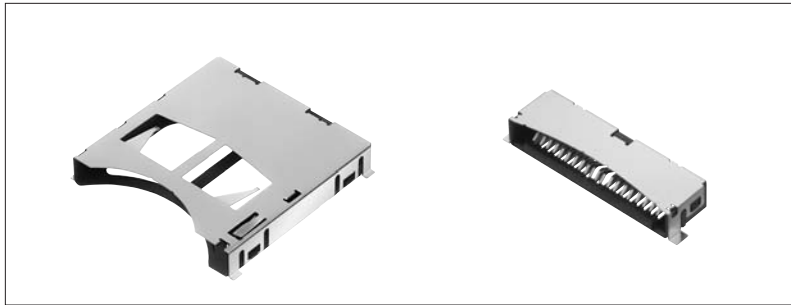


Connector for W-SIM

SCZA Series



High reliability contact structure best fit for portable devices.



Features

- Improved operability from long ejection stroke (5mm) and clear click feel.
- Good operational feel.
- Double contact-point for power and ground reduces risk of temporary power failure.
- Compact and low-profile suitable for portable devices.

Applications

- For mobile phones, PCs, and personal digital assistants

Typical Specifications

Items		Specifications
Structure	Applicable media	W-SIM
	Mounting type	Surface mounting type
	Mounting style	Standard mount
	Media ejection structure	Push-push type, Manual insertion/removal
Performance	Operating temperature range	-20°C to +60°C
	Voltage proof	500V AC 1minute
	Insulation resistance (Initial)	1,000MΩ min.
	Contact resistance (Initial)	100mΩ max.
	Insertion and removal cycle	10,000cycles

Product Line

Media ejection structure	Mounting system	Features	Stand-off (mm)	Packing system	Product No.	Drawing No.
Push-push type	Standard mount	Without boss L type	0	Tray	SCZA1A0100	1
		With boss L type			SCZA1A0200	2
		Without boss 0.6mm type			SCZA1A0300	3
		With boss 0.6mm type			SCZA1A0400	4
		Without boss 1.2mm type			SCZA1A0500	5
		With boss 1.2mm type			SCZA1A0600	6
Manual insertion/removal		With boss L type			SCZA2A0100	7
		Without boss 0.6mm type			SCZA2A0200	8

For SD Memory Card

For microSD™ Card

For SIM Card 8pins

For W-SIM

For Memory Stick Micro™

For Memory Stick™

Combine Type

For Compact Flash™

For PC cards supporting CardBus

For Express Card™

For CMOS Camera Module

Dimensions

Unit:mm

- For SD Memory Card
- For microSD™ Card
- For SIM Card 8pins
- For W-SIM**
- For Memory Stick Micro™
- For Memory Stick™
- Combine Type
- For Compact Flash™
- For PC cards supporting CardBus
- For Express Card™
- For CMOS Camera Module

No.	Style	PC board mounting hole dimensions (Viewed from the mounting face side)
1	<p>Push-push type Without boss L type</p>	<p> No parts area Land area No pattern area </p>
2	<p>Push-push type With boss L type</p>	<p> No Part Area Land No Pattern Area </p>

Dimensions

Unit:mm

No.	Style	PC board mounting hole dimensions (Viewed from the mounting face side)
3	<p>Push-push type Without boss 0.6mm type</p>	<p> <input type="checkbox"/> No Part Area <input checked="" type="checkbox"/> Land <input checked="" type="checkbox"/> No Pattern Area </p>
4	<p>Push-push type With boss 0.6mm type</p>	<p> <input type="checkbox"/> No Part Area <input checked="" type="checkbox"/> Land <input checked="" type="checkbox"/> No Pattern Area </p>

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No.	Style	PC board mounting hole dimensions (Viewed from the mounting face side)
5	<p>Push-push type Without boss 1.2mm type</p>	
6	<p>Push-push type With boss 1.2mm type</p>	

Dimensions

Unit:mm

No.	Style	PC board mounting hole dimensions (Viewed from the mounting face side)
7	<p>Manual insertion/removal With boss L type</p>	<p> :No Part Area :Land :No Pattern Area </p>
8	<p>Manual insertion/removal Without boss 0.6mm type</p>	<p> :No Part Area :Land :No Pattern Area </p>

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For PC cards supporting CardBus

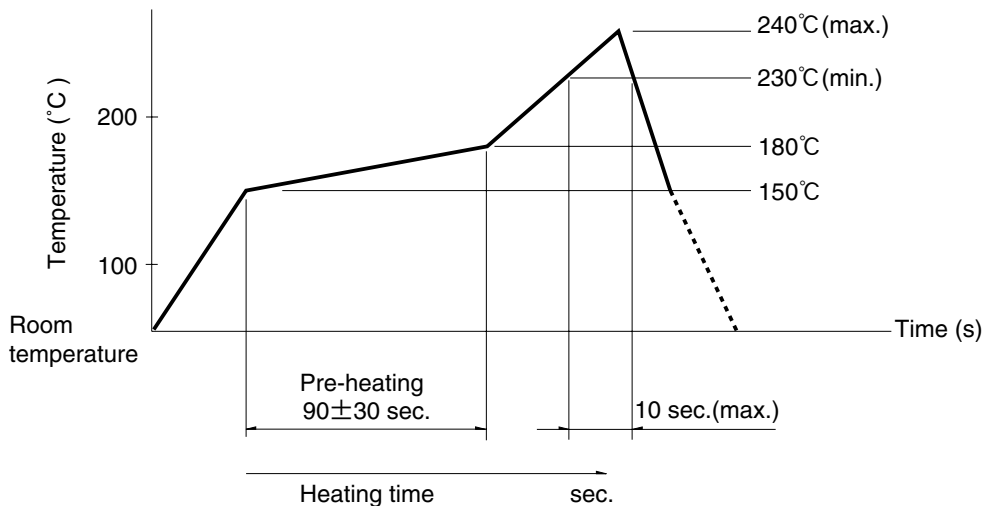
For Express Card™

For CMOS Camera Module

Soldering Conditions

Example of Reflow Soldering Condition (Reference)

1. Heating method: Double heating method with infrared heater.
2. Temperature measurement: Thermocouple 0.1 to 0.2 ϕ CA (K) or CC (T).
3. Temperature profile (Surface of products).



Cautions for using this product

1. When soldering terminals, there is a danger that load placed on the terminals may cause rattle, deformation or electrical degradation to occur depending on the conditions. Caution is therefore required.
2. Avoid use of water-soluble soldering flux, since it may corrode the product.
3. Check and conform to reflow soldering requirements under actual mass production conditions.
4. PC board warping may alter the characteristics. Please take this into consideration when designing patterns and layout.
5. The card specifications are provided by the above manufactures. Products by other manufactures may not be compliant with these specifications and are subject to change without prior notice.

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